

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Masaru SASAKI</td> <td>09/07/2012</td> </tr> <tr> <td>Kazuki MOYAMA</td> <td>09/07/2012</td> </tr> <tr> <td>Masaki INOUE</td> <td>09/06/2012</td> </tr> <tr> <td>Yoko NOTO</td> <td>10/01/2012</td> </tr> </tbody> </table>		Name	Execution Date	Masaru SASAKI	09/07/2012	Kazuki MOYAMA	09/07/2012	Masaki INOUE	09/06/2012	Yoko NOTO	10/01/2012
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Masaru SASAKI	09/07/2012										
Kazuki MOYAMA	09/07/2012										
Masaki INOUE	09/06/2012										
Yoko NOTO	10/01/2012										
RECEIVING PARTY DATA											
Name:	TOKYO ELECTRON LIMITED										
Street Address:	3-1, Akasaka 5-chome, Minato-ku										
City:	Tokyo										
State/Country:	JAPAN										
Postal Code:	107-6325										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13582523</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13582523						
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Application Number:	13582523										
CORRESPONDENCE DATA											
Fax Number:	8602860115										
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ATTORNEY DOCKET NUMBER:	BPL0192US										
NAME OF SUBMITTER:	Jaegyo Jang										
Total Attachments: 6											

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ASSIGNMENT

WHEREAS We,

**Masaru SASAKI** of c/o **TOKYO ELECTRON TECHNOLOGY DEVELOPMENT INSTITUTE, INC., 2-1, Osawa3-chome, Izumiku, Seidai City, Miyagi 981-3137, Japan,**

**Kazuki MOYAMA** of c/o **TOKYO ELECTRON TECHNOLOGY DEVELOPMENT INSTITUTE, INC., 1-8, Fuso-cho, Amagasaki City, Hyogo 660-0891, Japan,**

**Masaki INOUE** of c/o **TOKYO ELECTRON TECHNOLOGY DEVELOPMENT INSTITUTE, INC., 2-1, Osawa3-chome, Izumiku, Seidai City, Miyagi 981-3137, Japan**  
and

**Yoko NOTO** of c/o **TOKYO ELECTRON TECHNOLOGY DEVELOPMENT INSTITUTE, INC., 2-1, Osawa3-chome, Izumiku, Seidai City, Miyagi 981-3137, Japan**  
( h e r e i n a f t e r r e f e r r e d t o a s “  
ASSIGNORS”); have invented certain new and useful improvements in:

**PLASMA ETCHING METHOD, METHOD FOR PRODUCING SEMICONDUCTOR  
DEVICE, AND PLASMA ETCHING DEVICE**

which claims priority to **Japanese Patent Application No. 2010-048450, filed on March 4, 2010,** for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **TOKYO ELECTRON LIMITED** (hereinafter referred to as “ASSIGNEE”), a corporation organized and existing under the laws of the Country of Japan, having a place of business at **Address: 3-1, Akasaka 5-chome, Minato-ku, Tokyo 107-6325, Japan,** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and

in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: Sept. 7, 2012

Masaru Sasaki  
Masaru SASAKI

Date: Sept 7, 2012

Kazuki Moyama  
Kazuki MOYAMA

Date: \_\_\_\_\_

\_\_\_\_\_  
Masaki INOUE

Date: \_\_\_\_\_

\_\_\_\_\_  
Yoko NOTO

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Date: \_\_\_\_\_

\_\_\_\_\_  
**Masaru SASAKI**

Date: \_\_\_\_\_

\_\_\_\_\_  
**Kazuki MOYAMA**

Date: 6ep. 6. 2012

Masaki Inoue  
\_\_\_\_\_  
**Masaki INOUE**

Date: \_\_\_\_\_

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**Yoko NOTO**

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**Masaru SASAKI**

Date: \_\_\_\_\_

\_\_\_\_\_  
**Kazuki MOYAMA**

Date: \_\_\_\_\_

\_\_\_\_\_  
**Masaki INOUE**

Date: 1<sup>st</sup> Oct 2012

Yoko NOTO  
**Yoko NOTO**